

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S29	93	257/633.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S30	657	257/635.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S31	181	257/646.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S32	380	257/649.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S33	1065	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S34	2019	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S35	273	257/e23.001.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S36	283	((naota or iwao) near2 nakamura).inv. or (tomoharu near2 shimada). inv. or (kenichi near2 ishiguro).inv. or (sadao near2 nakashima).inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S37	25971	thermal adj treatment and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21

S38	6	S36 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S39	7960	(HITACHI adj KOKUSAI adj ELECTRIC).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S40	45	S37 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S41	12	(substrate near5 (support or board or plate)) near10 (10mm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S42	10	(substrate near10 (support or board or plate)) near15 (thickness near10(10mm))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S43	8	S42 not S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
S45	16	furnace with substrate with (holder support board) near15 (thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:30
S46	155554	((heat thermal anneal\$2) near15 treatment and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:32
S47	47285	((heat thermal anneal\$2) near15 treatment) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:32
S48	3400	(furnace chamber) with ((heat thermal anneal\$2) near15 treatment) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:33

S49	17784	(furnace chamber) with (heat thermal anneal\$2) near15 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:34
S50	2224	(furnace chamber) with (heat thermal anneal\$2) near15 substrate with (silicon si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:35
S53	3019	257/712.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/25 14:01
S54	2224	(furnace chamber) with (heat thermal anneal\$2) near15 substrate with (silicon si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/25 14:04
S55	1234	S54 and @ad<="20020927"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/25 14:04
S56	505	(furnace chamber) with (heat anneal\$3) and substrate with (board mount support) near10 (thickness width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/28 11:32
S57	217	S56 and @ad<="20020927"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/28 11:32
S58	3072	118/728.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/28 11:47
S59	915	118/720.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/28 11:47

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